

# **e-Manufacturing**

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# What's happening in USA & Japan for e-Manufacturing

- **May 17**
  - ISMT kicked off e-Diagnostics activity together with suppliers
- **June 29**
  - ISMT had a first workshop
- **Aug 28**
  - JEITA (then EIAJ) Electronic Devices Production Engineering Committee came to have “e-Mfg Study/Working Group”. (hereafter “JWG”) followed by a camp on equipment engineering on Sept. 15-17.
- **Oct 21**
  - ISMT and JWG had first F2F meeting in Austin

# e-Manufacturing Positions

## e-Business

### e-Manufacturing

product and pre-product's e-commerce  
chip buyers support  
spare parts logistics etc.

### Equipment Engineering

Real time control(APC/AEC)

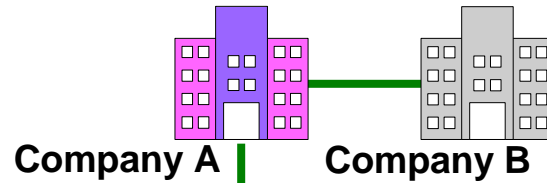
M-to-M difference management

Maintenance scheduling etc.

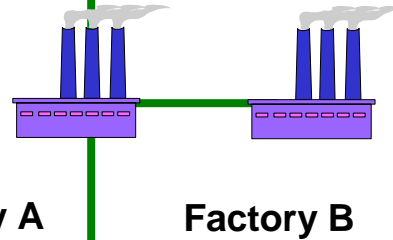
e-Diagnostics

# e-Manufacturing Hierarchy

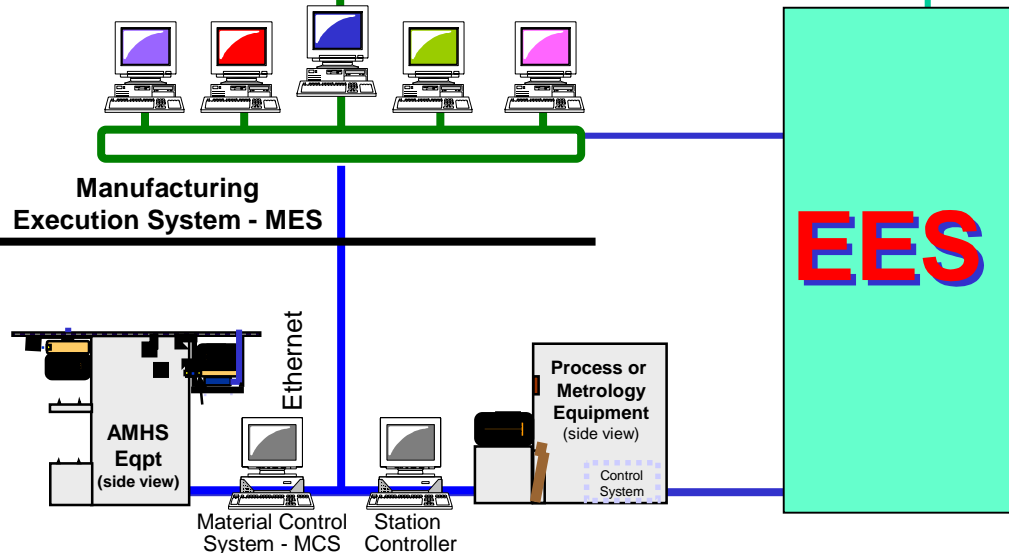
Company to Company  
(E-Commerce)



Factory to Factory  
(E-Factory)



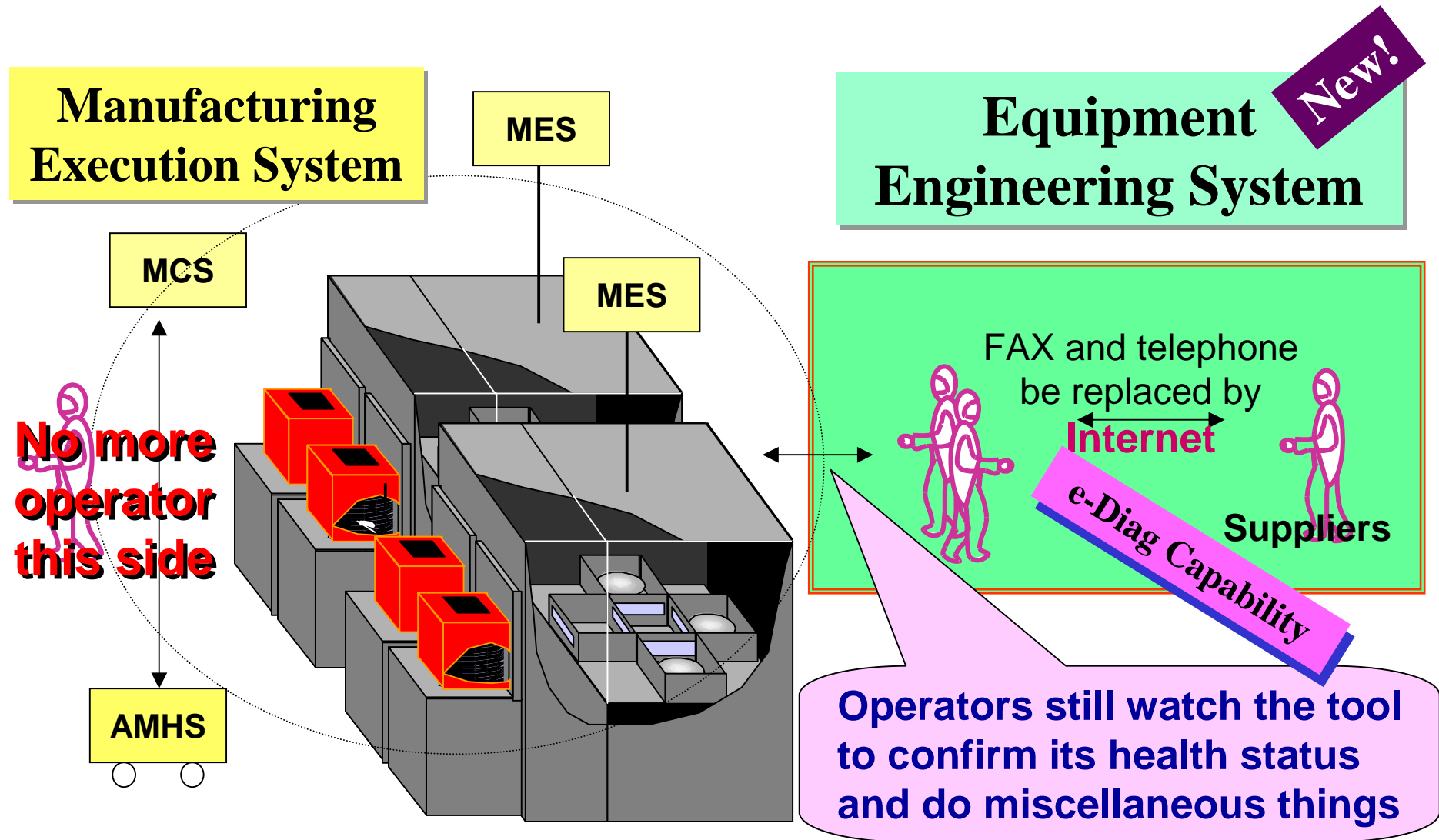
Within a Factory  
(E-Factory)



# Needs Building Up for e-Manufacturing

- e-Mfg includes
  - Product and pre-product's e-commerce
  - Chip buyers support
  - Spare parts logistics
  - Utilization of technical database of products/process
  - Equipment Engineering activity support
    - **Faster equipment improvement**
      - Prompt & clear recognition of equipment deficiency reasons
    - **Earlier detection of eq. malfunction**
    - **ISMT and JEITA has the common interest**
- e-Mfg requires a new frame work for  
***Equipment Engineering System***

# What EE System will replace?



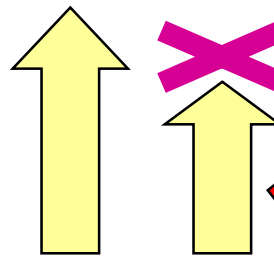
# Separate MES and EES

Solve discrepancy between  
what host and EE operation want to know

## Examples of Host view info

- Event reports for PW/NPW execution
- Alarm/warning report
- Macro tool operation status data for factory equipment management such as EFEM

Factory  
Host



Equipment  
(ARAMS)

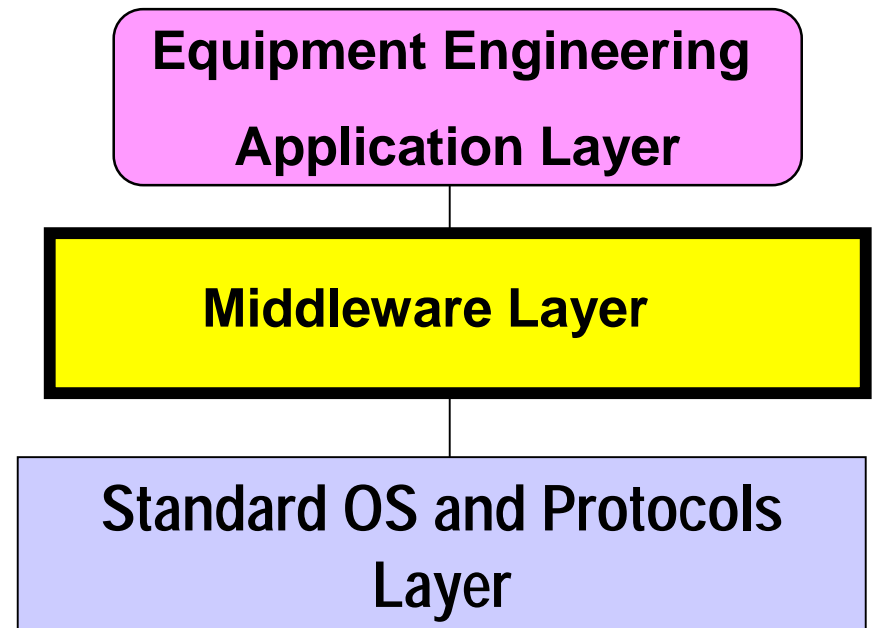
EE  
System

## Examples of Equipment view info

- Detailed ARAMS data for equipment performance Improvement
- Equipment malfunction symptom data
- Lives of consumables for planning preventive maintenance
- Detailed processing event report
- In process monitoring data

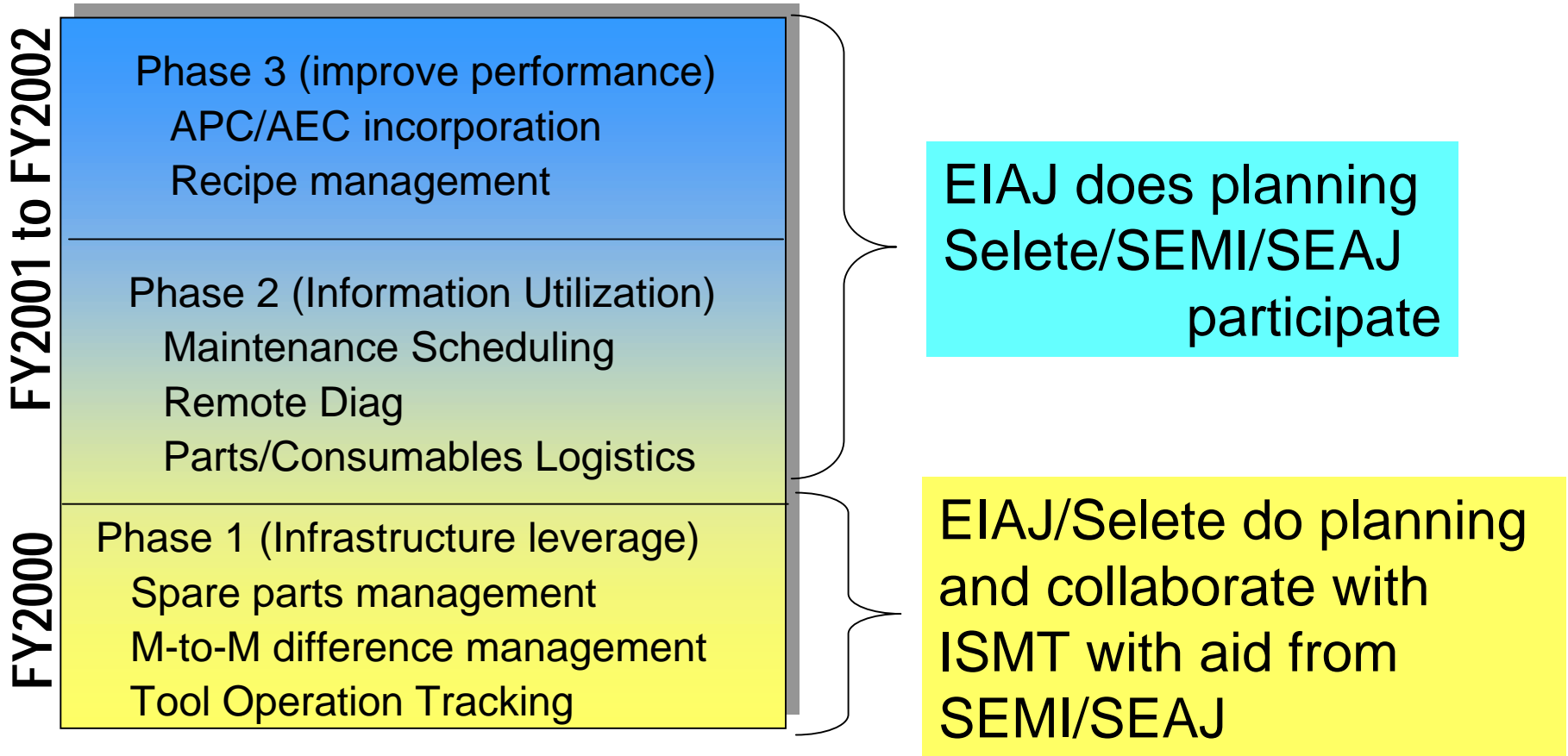
# What is IT requirement for EES?

- Independent EES IT structure from MES
  - should assure wide freedom in implementation styles
- How can we assure freedom?
  - Equipment Engineering Application Layer
  - Middleware Layer
    - provides open platform
    - key collaboration issue
  - Standard OS and Protocol Layer
    - Use the most common one
      - TCP/IP, XML, ??



# Activity Plan for e-Manufacturing in Japan

## EIAJ Activity Overview

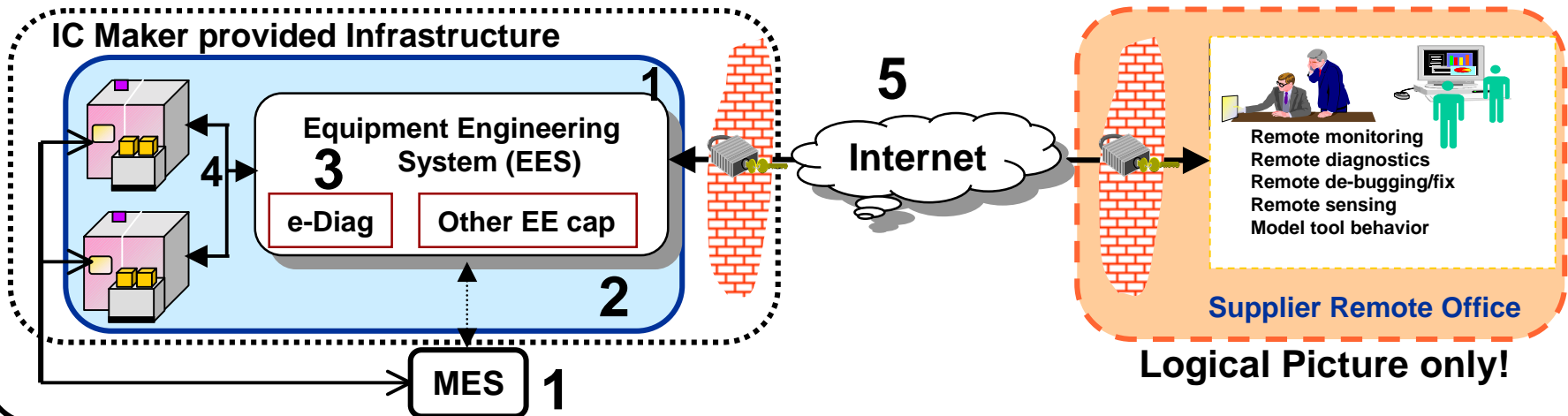


# JWG/ISMT Collaboration

- Sept 20, 2000 ISMT and JWG had the first VC
  - confirm international collaboration is a MUST
- Oct 21, 2000 ISMT and JWG had FTF meeting in Austin
  - had a consensus of EES and e-diagnostics system relation
  - agreed key system guidelines for e-diagnostics capability
  - made guideline development schedule

# Key System Guidelines for e-Diagnostic Capability

- 1. The e-Diag architecture shall be independent of current MES architecture**
  - e-Diag performance (up/down) shall not affect MES and tool performance
  - e-Diag and MES should be able to share information
- 2. The e-Diag architecture shall be server based**
- 3. The e-Diag architecture shall be Open (platform and application)**
- 4. Open standards are required between the tool and server**
  - Common data collection is open standards (e.g., EPT)
  - Specific data collection is open protocol (e.g., specific sensor output over FTP)
- 5. Open standards are required between the sever and supplier site**
- 6. Potential solutions must address worker, product, and equipment safety.**
- 7. Potential solutions must address security: network, communications, data encryption and other relevant issues.**



# Activity Organization for Global Collaboration

## EIAJ / ISMT Guideline development schedule

2001	<b>Phase 2 (Performance Improvement)</b> <b>APC/AEC (R2R, FDC)</b> <b>Recipe management</b> <b>Maintenance Scheduling</b> <b>M-to-M difference management</b> <b>Parts/Consumables Mgmt.</b>
2000	<b>Phase 1 (Infrastructure Leverage)</b> <b>EE platform concept</b> <b>e-Diagnostics</b> <b>Tool Operation Tracking</b>

# Summary

- **Need to have an industry consensus for e-Manufacturing**
  - Equipment engineering system shall have open structure so as to maximize tool performance.
  - Equipment engineering architecture shall be independent of current CIM system architecture.
- **Collaboration among device makers, equipment makers, and, software vendors is a must**
- **Need to develop new standardization process**
  - Prototype system development and standardization process is spiral.

# EES/e-Diagnostics 'new' Process

SEMICON Southwest

SEMICON Japan

???

???

Agree on Scope

Agree on Key Guidelines for e-diag

Roll out Guidelines for EES

Joint IC Makers and Suppliers

Jointly develop Spec for Phase 1 (USRD)

Jointly develop implementation Spec for Phase 2 (USRD)

Develop Emerging Standard (not using SEMI)

Iterations are necessary

Industry Prototypes

Develop Industry Roadmap

Finalize Standards with SEMI

★ Benefits suppliers and IC makers (both are users)